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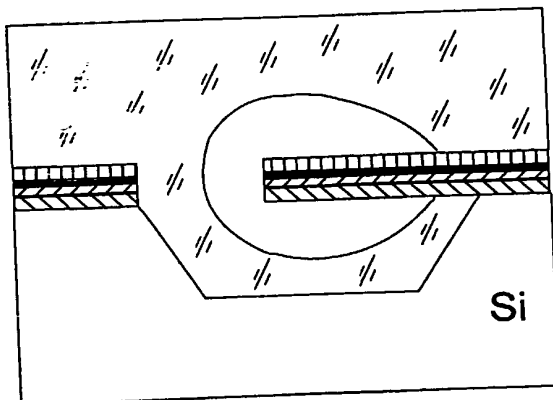
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(54) Title: METHOD FOR PRODUCING A PACKAGED INTEGRATED CIRCUIT WITH A MICROCAVITY



(57) Abstract: There is described a method for producing a pack-  
aged integrated circuit. The method comprises a first step of build-  
ing an integrated circuit having a micro-structure suspended above  
a micro-cavity, and having a heating element on the micro-struc-  
ture capable of heating itself and its immediate surroundings. A  
layer of protective material is then deposited on said micro-struc-  
ture such that at least a top surface of the micro-structure and an  
opening of the micro-cavity is covered, wherein the protective ma-  
terial is in a solid state at room temperature and can protect the  
micro-structure during silicon wafer dicing procedures and subse-  
quent packaging. The integrated circuit is packaged and an electric  
current is passed through the heating element such that a portion  
of the protective material is removed and an unobstructed volume  
is provided above and below the micro-structure.

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